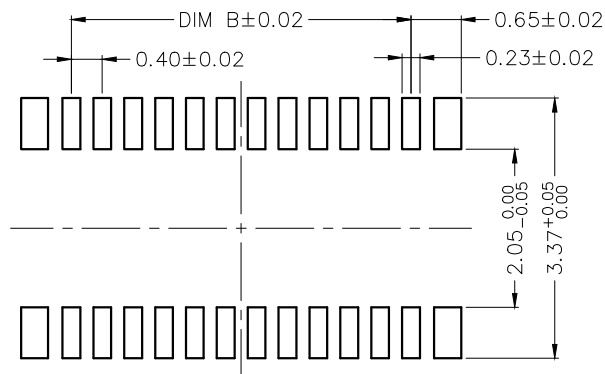
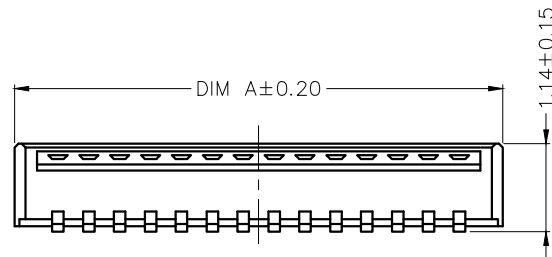
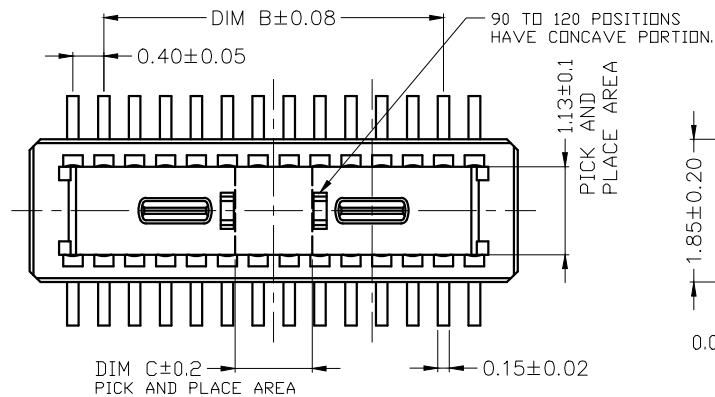
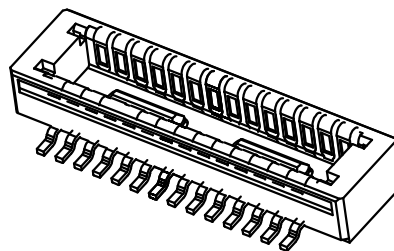
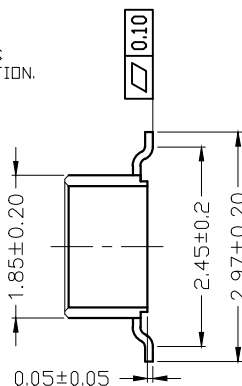




RECOMMENDED PCB LAYOUT



SPECIFICATIONS:

- 1.VOLTAGE/CURRENT RATING: 30V/AC, DC,0.3A;
 - 2.WITHSTANDING VOLTAGE: 100V AC/ONE MINUTE;
 - 3.INSULATION RESISTANCE: 50M Ω MIN/100V DC.;
 - 4.CONTACT RESISTANCE: 90M Ω MAX./1mA,20mV AC,1KHz;
 - 5.DURABILITY: 30 CYCLES;
 - 6.OPERATING TEMPERATURE RANGE: -35° C TO 85° C.
- MATERIAL:
- 1.INSULATOR: LCP UL 94V-0 BLACK;
 - 2.TERMINAL: PHOSPHOR BRONZE;
- PLATING:
- 1.TERMINAL: CONTACT AREA: GOLD 0.05μm"MIN.
SMT LEAD:GOLD 0.025μm" MIN.
UNDERPLATING:NICKEL 1μm" MIN.

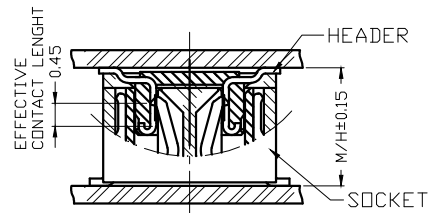
L B F * * — G * * P — B 0 R 0 1

- PACKING: R:REEL
0:STANDARD SPECIFICATIONS
COLOR:BLACK
P: PLUG
PIN
PLATING: G:GOLD FLASH
HEIGHT:11--1.14H
F:0.40 BTB
LXWCONN BTB CONNECTOR SERIES

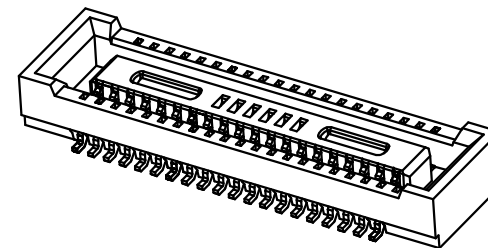
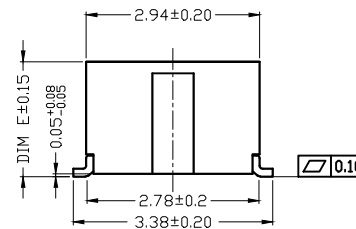
PIN NO.	DIM A	DIM B	DIM C
10	3.52	1.60	1.00
20	5.52	3.60	1.00
24	6.32	4.40	1.20
30	7.52	5.60	1.50
34	8.32	6.40	1.50
40	9.52	7.60	3.20
50	11.52	9.60	3.20
60	13.52	11.60	3.20
70	15.52	13.60	3.20
80	17.52	15.60	3.20
90	19.52	17.60	3.20
100	21.52	19.60	3.20
120	25.52	23.60	3.20

LXW 连兴旺电子(深圳)有限公司
connectivity LXWCONN ELECTRONICS(SHENZHEN)CO.,LTD

制图 (DR): Johnny 2023.07.03	品名(TITLE): BTB HEADER P0.40
审核 (CHKD): Tong	料号(PART NO): LBF**-G**P-BOR01
核准 (APPD): 2023.07.03	比例(SCALE): 1:1
	单位(UNITS): mm
	张数(SHEET): 1 OF 1
	图幅(SIZE): A4



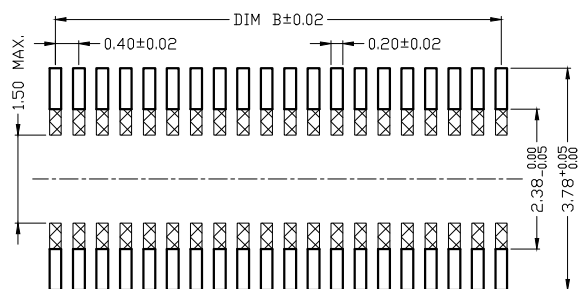
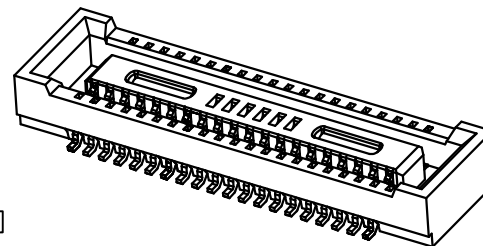
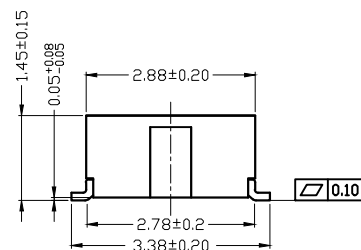
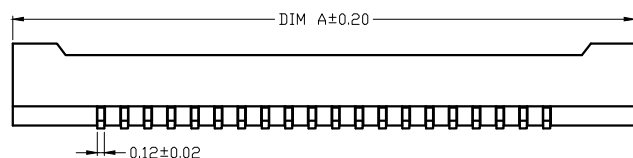
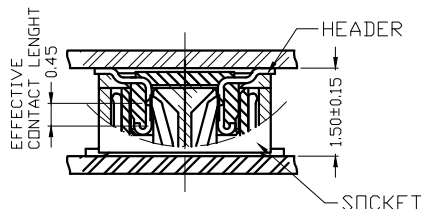
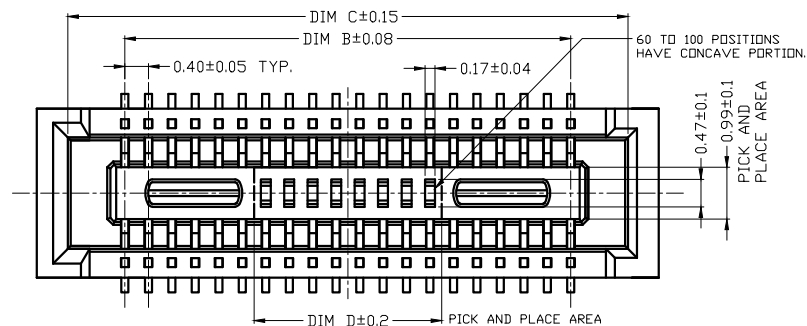
UNDERPLATING: NICKEL 1μm" MIN.



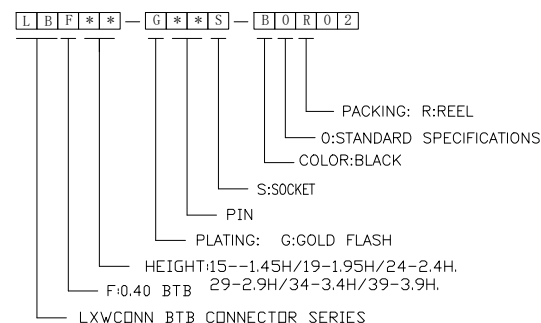
M/H	2.00	2.50	3.00	3.50	4.00
DIM E	1.95	2.40	2.90	3.40	3.90



一般公差	
GENERAL TOLERANCE	
.X	± 0.3
.XX	± 0.20
.XXX	± 0.10
ANGLES	$\pm 1^\circ$
版本 (REV)	A



RECOMMENDED PCB LAYOUT



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MATERIAL:

- 1.INSULATOR: LCP UL 94V-0 BLACK;
- 2.TERMINAL: PHOSPHOR BRONZE;

PLATING:

- 1.TERMINAL: CONTACT AREA: GOLD 0.05 μ m" MIN.
SMT LEAD: GOLD 0.025 μ m" MIN.
UNDERPLATING: NICKEL 1 μ m" MIN.

PIN NO.	DIM A	DIM B	DIM C	DIM D
10	4.60	1.60	3.55	1.00
20	6.60	3.60	5.55	1.00
24	7.40	4.40	6.35	1.20
30	8.60	5.60	7.55	1.50
34	9.40	6.40	8.35	1.50
40	10.60	7.60	9.55	3.20
50	12.60	9.60	11.55	3.20
60	14.60	11.60	13.55	3.20
70	16.60	13.60	15.55	3.20
80	18.60	15.60	17.55	3.20
90	20.60	17.60	19.55	3.20
100	22.60	19.60	21.55	3.20
120	26.60	23.60	25.55	3.20

LXW 连兴旺电子(深圳)有限公司
connectivity LXWCONN ELECTRONICS(SHENZHEN) CO.,LTD

制图 (DR): Johnny 2023.07.03 品名(TITLE): BTB SCOKET P0.40 H1.5
审核 (CHKD): 料号(PART NO): LBF**-G**S-BOR02
核准 (APPD): Tong 2023.07.03 比例(SCALE): 1:1 单位(UNITS): mm 张数(SHEET): 1 OF 1 图幅(SIZE): A4

修订 SER	修改摘要 REVISION DESCRIPTION	签名 SIGNATURE	日期 DATE

一般公差 GENERAL TOLERANCE
.X ±0.3
.XX ±0.20
.XXX ±0.10
ANGLES ±1°

